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A	<table><tr><th colspan="7">REVISIONS</th></tr><tr><th>PAGE</th><th>ZONE</th><th>REV</th><th>ECN</th><th>DESCRIPTION</th><th>DATE</th><th>APPROVED</th></tr><tr><td>ALL</td><td>-</td><td>**</td><td>109470</td><td>NEW RELEASE</td><td>08/21/01</td><td>N/A</td></tr><tr><td>ALL</td><td>-</td><td>*A</td><td>111367</td><td>REMOVE CAVITY DIM./ CHG. PKG. BODY DIM. TO MIN./MAX.</td><td>11/05/01</td><td>N/A</td></tr><tr><td>ALL</td><td>-</td><td>*B</td><td>117574</td><td>REMOVE DETAIL MARK AT 4 CORNERS BTM VIEW/ CHG. PIN 1 ID AT BTM VIEW.</td><td>07/24/02</td><td>N/A</td></tr><tr><td>ALL</td><td>-</td><td>*C</td><td>125371</td><td>ADD PKG. OPTION 2/CHG. ALL DIM.S TO MIN./MAX. AND MM[INCHES] /ADD JEDEC NOTE.</td><td>03/14/03</td><td>N/A</td></tr><tr><td>ALL</td><td>-</td><td>*D</td><td>127105</td><td>DELETE PKG. OPTION 2/ CHG. TITLE/ CHG. PART # ADD E-PAD NOTE</td><td>05/19/03</td><td>N/A</td></tr><tr><td>ALL</td><td>-</td><td>*E</td><td>489049</td><td>ADD U-GROOVE OPTION FOR CML BUILD</td><td>07/28/06</td><td>N/A</td></tr><tr><td>ALL</td><td>-</td><td>*F</td><td>514860</td><td>CORRECT REVISION "E" ECN NUMBER FROM 489772 TO 489049</td><td>10/12/06</td><td>N/A</td></tr><tr><td>ALL</td><td>-</td><td>*G</td><td>736321</td><td>REVISED DRAWING, DEFINED SOLDERABLE EXPOSED AREA. REMOVED CML OPTION. CHANGED SPEC. TITLE, CORRECTED EPAD DIMENSION</td><td>01/29/07</td><td>JSO</td></tr><tr><td rowspan="3">B</td><td>ALL</td><td>-</td><td>*H</td><td>2813378</td><td>Changed Template and Title from 56LD QFN 8 X 8mm PACKAGE OUTLINE (SUBCON PUNCH TYPE PKG with 6.1 x 6.1 EPAD) to PACKAGE OUTLINE, 56LD QFN 8X8X1.0 MM LF56/LY56 6.1X6.1 EPAD (SUBCON PUNCH TYPE).</td><td>11/24/09</td><td>QAD</td></tr><tr><td>ALL</td><td>-</td><td>*I</td><td>3159033</td><td>NO CHANGE</td><td>02/01/11</td><td>QAD</td></tr><tr><td>ALL</td><td>-</td><td>*J</td><td>4584955</td><td>Sunset Review, Changed drawing template.</td><td>12/02/14</td><td>QAD</td></tr><tr><td rowspan="10">C</td><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td rowspan="10">D</td><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr><tr><td colspan="5"></td></tr></table>					REVISIONS							PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED	ALL	-	**	109470	NEW RELEASE	08/21/01	N/A	ALL	-	*A	111367	REMOVE CAVITY DIM./ CHG. PKG. BODY DIM. TO MIN./MAX.	11/05/01	N/A	ALL	-	*B	117574	REMOVE DETAIL MARK AT 4 CORNERS BTM VIEW/ CHG. PIN 1 ID AT BTM VIEW.	07/24/02	N/A	ALL	-	*C	125371	ADD PKG. OPTION 2/CHG. ALL DIM.S TO MIN./MAX. AND MM[INCHES] /ADD JEDEC NOTE.	03/14/03	N/A	ALL	-	*D	127105	DELETE PKG. OPTION 2/ CHG. TITLE/ CHG. PART # ADD E-PAD NOTE	05/19/03	N/A	ALL	-	*E	489049	ADD U-GROOVE OPTION FOR CML BUILD	07/28/06	N/A	ALL	-	*F	514860	CORRECT REVISION "E" ECN NUMBER FROM 489772 TO 489049	10/12/06	N/A	ALL	-	*G	736321	REVISED DRAWING, DEFINED SOLDERABLE EXPOSED AREA. REMOVED CML OPTION. CHANGED SPEC. TITLE, CORRECTED EPAD DIMENSION	01/29/07	JSO	B	ALL	-	*H	2813378	Changed Template and Title from 56LD QFN 8 X 8mm PACKAGE OUTLINE (SUBCON PUNCH TYPE PKG with 6.1 x 6.1 EPAD) to PACKAGE OUTLINE, 56LD QFN 8X8X1.0 MM LF56/LY56 6.1X6.1 EPAD (SUBCON PUNCH TYPE).	11/24/09	QAD	ALL	-	*I	3159033	NO CHANGE	02/01/11	QAD	ALL	-	*J	4584955	Sunset Review, Changed drawing template.	12/02/14	QAD	C																																																			D																																																		
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THIS DRAWING CONTAINS INFORMATION WHICH IS THE PROPRIETARY PROPERTY OF CYPRESS SEMICONDUCTOR CORPORATION. THIS DRAWING IS RECEIVED IN CONFIDENCE AND ITS CONTENTS MAY NOT BE DISCLOSED WITHOUT WRITTEN CONSENT OF CYPRESS SEMICONDUCTOR CORPORATION.				PACKAGE CODE(S)	LF56 LY56																																																																																																																																																																																																		
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